HB16 Wedge & Ball Bonder
Motorized Z- & Y- Axes

+ Wedge, Ball, Bump and Ribbon bonding
+ 17μ to 75μ Wire and 25μ x 250μ Ribbon
+ 6,5” TFT Touch Screen
+ Deep-Access Wedge 16mm / Ball 13mm
+ Bond Arm Length 165mm
+ 100 Program Storage Capacities
+ Motorized Z- & Y-Axis
+ Programmable Loop Profile
+ USB Backup
+ Electronic Ball Size Control

+ Pick & Place Option
+ Pull Tester Option
+ Copper Bonding Option
HB16 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB16 is a Bench Top Size Wire Bonder, ideal for laboratories, pilot and small scale production lines. One Bond Head for bonding in Ball/Wedge or Wedge/Wedge bonding mode. Only tool change necessary. Easy operation with TFT Touch Screen and direct access and simple adjustment of all bond parameters.

Technical Specifications

<table>
<thead>
<tr>
<th>Bonding Method</th>
<th>Wedge-Wedge, Ball-Wedge, Ribbon- &amp; Bump- bonding</th>
</tr>
</thead>
<tbody>
<tr>
<td>Gold wire diameter</td>
<td>17 - 75 µm (0.7 - 3&quot;)</td>
</tr>
<tr>
<td>Aluminium wire diameter</td>
<td>17 - 75 µm (0.7 - 3&quot;)</td>
</tr>
<tr>
<td>Ribbon size</td>
<td>max. 25 x 250 µm (1 x 9.8&quot;)</td>
</tr>
<tr>
<td>Ultrasonic system</td>
<td>63.3 kHz Transducer PLL Control</td>
</tr>
<tr>
<td>Ultrasonic power</td>
<td>0 - 10 Watt Output</td>
</tr>
<tr>
<td>Bond time</td>
<td>0 - 20000 msec.</td>
</tr>
<tr>
<td>Bond force</td>
<td>5 - 150 cN (350 cN option)</td>
</tr>
<tr>
<td>Bonding tool</td>
<td>1.58 Ø 19mm length (0.0624&quot; x 0.750&quot;)</td>
</tr>
<tr>
<td>Motorised Wire Spool</td>
<td>50.8 mm (2&quot;)</td>
</tr>
<tr>
<td>Wire termination</td>
<td>Bond Head Tear / Clamp Tear</td>
</tr>
<tr>
<td>Wire feed angle</td>
<td>90°</td>
</tr>
<tr>
<td>Clamp movement</td>
<td>Motorized, Up / Down</td>
</tr>
<tr>
<td>Ball size control</td>
<td>Electronic</td>
</tr>
<tr>
<td>Motorized Z travel</td>
<td>17 mm (0.67&quot;)</td>
</tr>
<tr>
<td>Motorized Y travel</td>
<td>10 mm (0.39&quot;)</td>
</tr>
<tr>
<td>Throat depth</td>
<td>165 mm (6.5&quot;)</td>
</tr>
<tr>
<td>Fine Table motion</td>
<td>10 mm (0.39&quot;)</td>
</tr>
<tr>
<td>Mouse ratio</td>
<td>6.1</td>
</tr>
</tbody>
</table>

Temperature controller: up to 250°C +/- 1°C
Electrical Requirements: 100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions: 680 [27"] x 640 [25"] x 490 mm [19”]
Weight: Net 42 kg
Industry Standards: CE standards

Accessories:
- H26 Heater Stage with Pick & Place
- H21 Heater Stage 100 x 100mm
- H50 Spotlight Targeting System
- H69 Bond Starter Kit
- H51 Manual Z-Axis Control
- H89 Video Targeting System

Specifications are subject to change without prior notice.